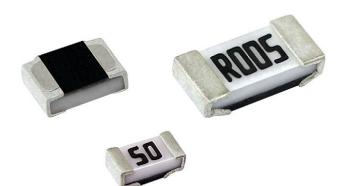
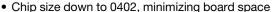


Metal Foil Current Sense Resistors, Low Value (Down to 0.001 Ω)



FEATURES

- · Ultra low sensing resistance
- Low TCR (down to 50 ppm/°C)



Sulfur resistant

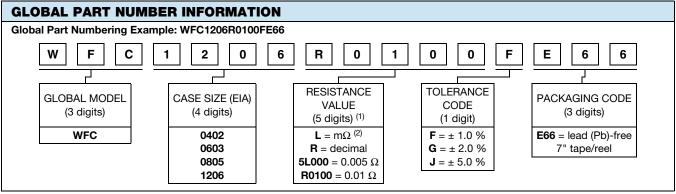
HALOGEN FREE

 Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

APPLICATIONS

- Switching power supply
- Voltage regulation module
- DC/DC converter, adaptor, battery pack, charger
- · Pad and cell phone
- · Power management

| STANDARD ELECTRICAL SPECIFICATIONS | | | | | | | | | |
|------------------------------------|------|-------------------|----------------|---------------------------------|--------------------------------------|--|--|--|--|
| GLOBAL MODEL | SIZE | POWER RATING W | TOLERANCE % | RESISTANCE VALUE RANGE Ω | WEIGHT (typical) g/1000 pieces | | | | |
| WFC0402 | 0402 | 0.125 | ± 1, ± 2, ± 5 | 0.003 to 0.05 | 1.1 | | | | |
| WFC0603 | 0603 | 0.33 | ± 1, ± 2, ± 5 | 0.001 to 0.005 | 3.3 | | | | |
| | 0603 | 0.25 | ± 1, ± 2, ± 5 | 0.0051 to 0.03 | 3.3 | | | | |
| WFC0805 | 0805 | 0.50 | ± 1, ± 2, ± 5 | 0.001 to 0.04 | 6.8 | | | | |
| WFC1206 | 1206 | 1.0 | ± 1, ± 2, ± 5 | 0.001 to 0.05 | 17.4 | | | | |
| | 1206 | 0.5 | ± 1, ± 2, ± 5 | 0.100 to 0.18 | 17.4 | | | | |



Notes

(1) Resistance values are available per E12 and E24 decades; www.vishay.com/doc?28372

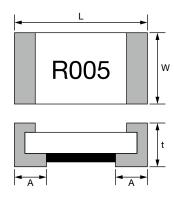
 $^{(2)}$ Use "L" for resistance values < 0.01 Ω

Vishay Dale



| TECHNICAL SPECIFICATIONS | | | | | | | | |
|-----------------------------|--------|---|--|---|--|--|--|--|
| PARAMETER | UNIT | RESISTOR CHARACTERISTICS | | | | | | |
| PARAMETER | UNII | WFC0402 | WFC0603 | WFC0805 | WFC1206 | | | |
| | ppm/°C | \pm 100 for 8 m Ω to 50 m Ω | \pm 75 for 10 m Ω to 30 m Ω | \pm 50 for 10.1 m Ω to 40 m Ω | \pm 50 for 10.1 m Ω to 180 m Ω | | | |
| Temperature coefficient | | \pm 150 for 3 m Ω to 7 m Ω | \pm 150 for 5.1 m Ω to 9 m Ω | \pm 100 for 1 m Ω to 10 m Ω | \pm 100 for 1 m Ω to 10 m Ω | | | |
| | | = | \pm 100 for 1 m Ω to 5 m Ω | - | - | | | |
| Operating temperature range | °C | -55 to +170 | | | | | | |
| Maximum working voltage | V | $(P \times R)^{1/2}$ | | | | | | |
| Maximum element temperature | °C | 170 | | | | | | |

DIMENSIONS in inches (millimeters)

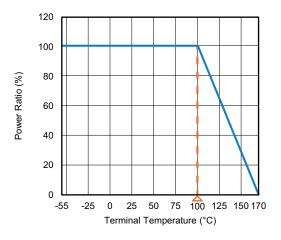


| TYPE | RESISTANCE | DIMENSIONS (in millimeters) | | | | | | |
|-------------|---------------------|-----------------------------|-------------|-----------------|-------------|--|--|--|
| (INCH SIZE) | RANGE (m Ω) | L | W | t | Α | | | |
| WFC0402 | 7.1 to 50 | 1.00 - 0.10 | 0.55 + 0.10 | 0.45 + 0.10 | 0.25 ± 0.10 | | | |
| | 3 to 7 | 1.00 ± 0.10 | 0.55 ± 0.10 | 0.45 ± 0.10 | 0.35 ± 0.10 | | | |
| WFC0603 | 5 to 30 | 1.60 ± 0.10 | 0.80 ± 0.10 | 0.55 ± 0.15 | 0.30 ± 0.20 | | | |
| | 1 to 5 | 1.00 ± 0.10 | 0.95 ± 0.25 | 0.60 ± 0.25 | 0.55 ± 0.20 | | | |
| WFC0805 | 5 to 40 | 2.00 ± 0.20 | 1.30 ± 0.15 | 0.70 ± 0.15 | 0.45 ± 0.20 | | | |
| WFCUOUS | 1 to 5 | 2.10 ± 0.20 | 1.40 ± 0.20 | 0.60 max. | 0.60 ± 0.20 | | | |
| WFC1206 | 1 to 3 | 3.10 ± 0.20 | 1.55 ± 0.20 | 0.75 ± 0.25 | 1.30 ± 0.20 | | | |
| | 3 to 180 | 3.10 ± 0.20 | 1.55 ± 0.20 | 0.80 ± 0.15 | 0.55 ± 0.20 | | | |

Note

• 0402 has no marking; 0603, 0805, 1206 marking shows two digits for resistance

DERATING





PERFORMANCES

| ENV | IRONMENTAL PERFOR | RMANCE | |
|-----|---|---|---|
| NO. | ITEM | TEST CONDITION | SPECIFICATION |
| 1 | Short time overload | 5 times rated power for 5 seconds (JIS-C5202-5.5) | ΔR : ± (1 % + 0.0005 Ω) |
| 2 | Temperature coefficient of resistance (TCR) | +25 °C / +125 °C (JIS-C5202-5.2) TCR (ppm/°C) = $\frac{\Delta R}{R \times \Delta t} \times 10^6$ | Refer to Electrical Specification |
| 3 | Damp heat with load | The specimens shall be placed in a chamber and subjected to a relative humidity of 90 % to 95 % and a temperature of 40 °C ± 2 °C for the period of 1000 hours with applying rated power 1.5 hours ON and 0.5 hour OFF. (MIL-STD-202, method 103) | ΔR: ± (1 % + 0.0005 Ω) |
| 4 | High temperature exposure | The chip (mounted on board) is exposed in the heat chamber 125 °C \pm 3 °C for 1000 hours. (JIS-C5202-7.2) | ΔR: ± (1 % + 0.0005 Ω) |
| 5 | Load life | Apply rated power at 70 $^{\circ}$ C \pm 2 $^{\circ}$ C for 1000 hours with 1.5 hours ON and 0.5 hour OFF. (JIS-C5202-7.10) | ΔR : ± (1 % + 0.0005 Ω) |
| 6 | Rapid change of temperature | The chip (mounted on board) is exposed, -55 °C \pm 3 °C (30 min.) / +155 °C \pm 2 °C (30 min.) for 5 cycles. The following conditions as the following figure. (JIS-C5202-7.4) Ambient temperature +155 (\pm 2) °C +25 (\pm 2) °C +25 (\pm 3) °C 1 cycle | ΔR: ± (1 % + 0.0005 Ω) |

| FUN | FUNCTION PERFORMANCE | | | | | | | |
|-----|---------------------------|--|---|--|--|--|--|--|
| NO. | ITEM | TEST CONDITION | SPECIFICATION | | | | | |
| 1 | Bending strength | Mount the chip to test substrate. Apply pressure in direction of arrow unit band width reaches 2 mm (+0.2 / -0 mm) illustrated in the figure below and hold for 10 s ± 1 s. (JIS-C5202-6.1) Position before bend Testing printed circuit board | ΔR : ± (1 % + 0.0005 Ω) | | | | | |
| 2 | Solvent resistance | Complete immersion of specimens in isopropyl alcohol for 3 (+5, -0) min. 25 $^{\circ}$ C \pm 5 $^{\circ}$ C. (MIL-STD-202, method 215) | Verify marking permanency. (not required for laser etched parts or parts with no marking) | | | | | |
| 3 | Resistance to solder heat | The specimen chip shall be immersed into the flux specified in the solder bath 260 $^{\circ}$ C \pm 5 $^{\circ}$ C for 10 s \pm 1 s. (MIL-STD-202, method 210) | ΔR : ± (1 % + 0.0005 Ω) | | | | | |



| FUN | FUNCTION PERFORMANCE | | | | | | | |
|-----|----------------------|--|---|--|--|--|--|--|
| NO. | ITEM | TEST CONDITION | SPECIFICATION | | | | | |
| 4 | Solderability | The specimen chip shall be immersed into the flux specified in the solder bath 235 °C ± 5 °C for 2 s ± 0.5 s. It shall be immersed to a point 10 mm from its root. (Sn96.5 / Ag3.0 / Cu0.5) (JIS-C5 202-6.11) Molten solder Specimen SMD h = 10 mm H = 10 mm min. | Solder shall be covered 95 % or more of the electrode area. | | | | | |

Notes

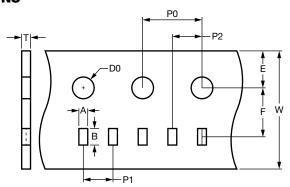
- 0.5 W with total solder pad trace size of 100 mm². The surface temperature of component should below 100 °C
- 1.0 W with total solder pad trace size of 100 mm². The surface temperature of component should below 100 °C

| TAPE PACKAGING SPECIFICATIONS | | | | | | | |
|---------------------------------|---------------------|-------------|-------------|--|--|--|--|
| MODEL | | | | | | | |
| MODEL | TAPE WIDTH | DIAMETER | PIECES/REEL | | | | |
| WFC0402 | Embossed paper tape | 178 mm / 7" | 10 000 | | | | |
| WFC0603, WFC0805, WFC1206 | Embossed paper tape | 178 mm / 7" | 5000 | | | | |

Note

• Embossed carrier tape per EIA (EIAJ)

PAPER TAPE SPECIFICATIONS



| TYPE | RESISTANCE | CARRIER DIMENSIONS (in millimeters) | | | | | | | | | |
|---------|----------------------------------|-------------------------------------|---------------|------------|----------------|---------------|---------------|---------------|----------------|-----------------|----------------|
| ITPE RA | RANGE | Α | В | E | F | W | P0 | P1 | P2 | D0 | Т |
| WFC0402 | 3 m Ω to 50 m Ω | 0.7 ± 0.05 | 1.2 ± 0.05 | 1.75 ± 0.1 | 3.5 ± 0.05 | 8.0 ± 0.2 | 4.0 ± 0.1 | 2.0 ± 0.1 | 2.0 ± 0.05 | 1.55 ± 0.05 | 0.6 ± 0.1 |
| WFC0603 | 1 m Ω to 5 m Ω | 1.4 ± 0.1 | 1.9 ± 0.1 | 1.75 ± 0.1 | 3.5 ± 0.05 | 8.0 ± 0.2 | 4.0 ± 0.1 | 4.0 ± 0.1 | 2.0 ± 0.05 | 1.55 ± 0.05 | 0.75 ± 0.1 |
| WFC0603 | 5.1 m Ω to 30 m Ω | 1.1 ± 0.1 | 1.9 ± 0.1 | 1.75 ± 0.1 | 3.5 ± 0.05 | 8.0 ± 0.2 | 4.0 ± 0.1 | 4.0 ± 0.1 | 2.0 ± 0.05 | 1.55 ± 0.05 | 0.70 ± 0.1 |
| WFC0805 | 1 m Ω to 5 m Ω | 2.4 ± 0.1 | 1.9 ± 0.1 | 1.75 ± 0.1 | 3.5 ± 0.05 | 8.0 ± 0.2 | 4.0 ± 0.1 | 4.0 ± 0.1 | 2.0 ± 0.05 | 1.55 ± 0.05 | 0.75 ± 0.1 |
| WFC0805 | 5.1 m Ω to 40 m Ω | 1.6 ± 0.1 | 2.4 ± 0.1 | 1.75 ± 0.1 | 3.5 ± 0.05 | 8.0 ± 0.2 | 4.0 ± 0.1 | 4.0 ± 0.1 | 2.0 ± 0.05 | 1.55 ± 0.05 | 0.97 ± 0.1 |
| WFC1206 | 1 m Ω to 3 m Ω | 2.0 ± 0.1 | 3.6 ± 0.1 | 1.75 ± 0.1 | 3.5 ± 0.05 | 8.0 ± 0.2 | 4.0 ± 0.1 | 4.0 ± 0.1 | 2.0 ± 0.05 | 1.55 ± 0.05 | 0.87 ± 0.1 |
| WFC1206 | 3.1 m Ω to 180 m Ω | 2.0 ± 0.1 | 3.6 ± 0.1 | 1.75 ± 0.1 | 3.5 ± 0.05 | 8.0 ± 0.2 | 4.0 ± 0.1 | 4.0 ± 0.1 | 2.0 ± 0.05 | 1.55 ± 0.05 | 0.97 ± 0.1 |

Notes

Embossed carrier tape per EIA (EIAJ)

Revision: 16-Mar-2022

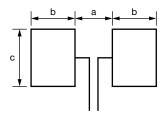
Additional packaging details at www.vishay.com/doc?20051



STORAGE CONDITIONS

Temperature: 5 °C to 35 °C, humidity: 40 % to 75 %

RECOMMENDED SOLDER PAD LAYOUT



| TYPE | PAD LAYOUT DIMENSIONS (in millimeters) | | | | | |
|--|--|------|------|--|--|--|
| TIPE | а | b | С | | | |
| 0402 (7.1 m Ω to 50 m Ω) | 0.50 | 0.50 | 0.60 | | | |
| 0402 (3 m Ω to 7 m Ω) | 0.30 | 0.60 | 0.60 | | | |
| 0603 (9.1 m Ω to 30 m Ω) | 0.90 | 0.70 | 1.00 | | | |
| 0603 (5 m Ω to 9 m Ω) | 0.60 | 0.90 | 1.00 | | | |
| 0805 (1 mΩ to 5 mΩ) | 0.80 | 1.60 | 1.45 | | | |
| 0805 (5.1 m Ω to 40 m Ω) | 1.20 | 1.20 | 1.40 | | | |
| 1206 (1 mΩ to 3 mΩ) | 0.40 | 1.80 | 2.20 | | | |
| 1206 (3.1 m Ω to 180 m Ω) | 2.20 | 1.30 | 1.80 | | | |

Note

• Recommend to use the steel plate which thickness > 100 µm to avoid the insufficient solder height

SOLDERING RECOMMENDATIONS

- Peak reflow temperatures and durations:
 - IR reflow peak = 260 °C max. for 10 s
 - Wave solder = 260 °C max. for 10 s
- Compatible with lead and lead (Pb)-free solder reflow processes
- Recommended IR reflow profile for surface mount devices: www.vishay.com/doc?31052



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